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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21367cnfa-w4

1.1.2 Specifications

Tables 1.1 and 1.2 outline the Specifications for R8C/36C Group.

Table 1.1 Specifications for R8C/36C Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C CPU core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns (f(XIN) = 20 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 1.8 to 5.5 V) • Multiplier: 16 bits × 16 bits → 32 bits • Multiply-accumulate instruction: 16 bits × 16 bits + 32 bits → 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM, Data flash	Refer to **Table 1.3 Product List for R8C/36C Group**
Power Supply Voltage Detection	Voltage detection circuit	• Power-on reset • Voltage detection 3 (detection level of voltage detection 0 and voltage detection 1 selectable)
I/O Ports	Programmable I/O ports	• Input-only: 1 pin • CMOS I/O ports: 59, selectable pull-up resistor • High current drive ports: 59
Clock	Clock generation circuits	• 4 circuits: XIN clock oscillation circuit, XCIN clock oscillation circuit (32 kHz), High-speed on-chip oscillator (with frequency adjustment function), Low-speed on-chip oscillator • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
		Real-time clock (timer RE)
Interrupts		• Interrupt Vectors: 69 • External: 9 sources ($\overline{\text{INT}}$ × 5, key input × 4) • Priority levels: 7 levels
Watchdog Timer		• 14 bits × 1 (with prescaler) • Reset start selectable • Low-speed on-chip oscillator for watchdog timer selectable
DTC (Data Transfer Controller)		• 1 channel • Activation sources: 39 • Transfer modes: 2 (normal mode, repeat mode)
Timer	Timer RA	8 bits × 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits × 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits × 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits × 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)

Table 1.2 Specifications for R8C/36C Group (2)

Item	Function	Specification
Timer	Timer RE	8 bits × 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits × 1 Input capture mode (input capture circuit), output compare mode (output compare circuit)
	Timer RG	16 bits × 1 (with 2 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 1 pin), phase counting mode (available automatic measurement for the counts of 2-phase encoder)
Serial Interface	UART0, UART1	Clock synchronous serial I/O/UART × 2 channel
	UART2	Clock synchronous serial I/O, UART, I^2C mode (I^2C bus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 (shared with I^2C bus)
I^2C bus		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
D/A Converter		8-bit resolution × 2 circuits
Comparator B		2 circuits
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance:10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • Background operation (BGO) function (data flash)
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current consumption		Typ. 7.0 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 4.0 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2.0 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		−20 to 85°C (N version) −40 to 85°C (D version) (1)
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin TQFP • Package code: PTQP0064LB-A

Note:
1. Specify the D version if D version functions are to be used.

1.2 Product List

Tables 1.3 and 1.4 list Product List for R8C/36C Group. Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/36C Group.

Table 1.3 Product List for R8C/36C Group (1) Current of Nov 2010

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data flash				
R5F21364CNFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version	
R5F21365CNFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CNFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CNFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CNFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACNFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CNFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CNFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CNFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CNFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CNFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACNFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CNFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CNFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CNFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CNFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CNFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACNFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCNFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		
R5F21364CNXXXFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version	Factory programming product (1)
R5F21365CNXXXFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CNXXXFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CNXXXFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CNXXXFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACNXXXFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCNXXXFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CNXXXFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CNXXXFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CNXXXFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CNXXXFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CNXXXFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACNXXXFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCNXXXFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CNXXXFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CNXXXFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CNXXXFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CNXXXFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CNXXXFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACNXXXFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCNXXXFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		

(D): Under development

Note:

1. The user ROM is programmed before shipment.

Table 1.4 Product List for R8C/36C Group (2) Current of Nov 2010

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data flash				
R5F21364CDFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	D version	
R5F21365CDFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CDFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CDFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CDFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACDFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCDFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CDFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CDFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CDFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CDFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CDFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACDFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCDFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CDFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CDFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CDFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CDFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CDFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACDFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCDFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		
R5F21364CDXXXFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version	Factory programming product
R5F21365CDXXXFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CDXXXFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CDXXXFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CDXXXFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACDXXXFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCDXXXFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CDXXXFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CDXXXFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CDXXXFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CDXXXFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CDXXXFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACDXXXFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCDXXXFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CDXXXFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CDXXXFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CDXXXFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CDXXXFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CDXXXFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACDXXXFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCDXXXFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		

(D): Under development

Note:

1. The user ROM is programmed before shipment.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

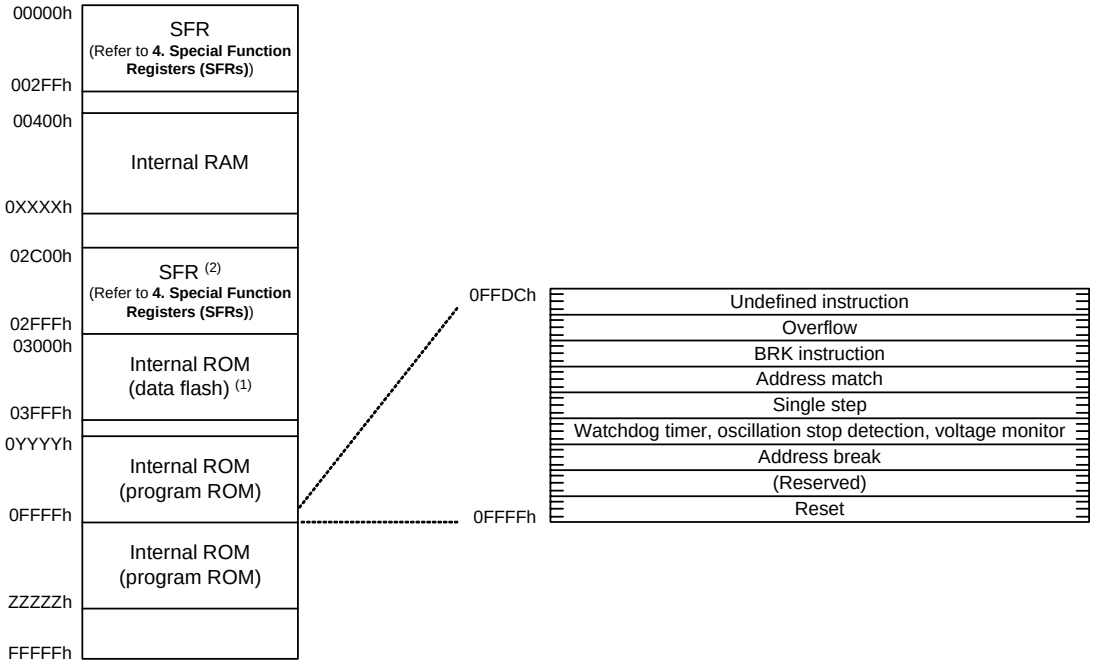
ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.



Notes:
1. The data flash indicates block A (1 Kbyte), block B (1 Kbyte), block C (1 Kbyte), and block D (1 Kbyte).
2. The SFR areas for the DTC and other modules are allocated to addresses 02C00h to 02FFFh.
3. The blank areas are reserved and cannot be accessed by users.

Part Number	Internal ROM			Internal RAM	
	Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh
R5F21364CNFP, R5F21364CDFP, R5F21364CNFA, R5F21364CDFA, R5F21364CNFB, R5F21364CDFB, R5F21364CNXXXFP, R5F21364CDXXXFP, R5F21364CNXXXFA, R5F21364CDXXXFA, R5F21364CNXXXFB, R5F21364CDXXXFB	16 Kbytes	0C000h	–	1.5 Kbytes	009FFh
R5F21365CNFP, R5F21365CDFP, R5F21365CNFA, R5F21365CDFA, R5F21365CNFB, R5F21365CDFB, R5F21365CNXXXFP, R5F21365CDXXXFP, R5F21365CNXXXFA, R5F21365CDXXXFA, R5F21365CNXXXFB, R5F21365CDXXXFB	24 Kbytes	0A000h	–	2 Kbytes	00BFFh
R5F21366CNFP, R5F21366CDFP, R5F21366CNFA, R5F21366CDFA, R5F21366CNFB, R5F21366CDFB, R5F21366CNXXXFP, R5F21366CDXXXFP, R5F21366CNXXXFA, R5F21366CDXXXFA, R5F21366CNXXXFB, R5F21366CDXXXFB	32 Kbytes	08000h	–	2.5 Kbytes	00DFFh
R5F21367CNFP, R5F21367CDFP, R5F21367CNFA, R5F21367CDFA, R5F21367CNFB, R5F21367CDFB, R5F21367CNXXXFP, R5F21367CDXXXFP, R5F21367CNXXXFA, R5F21367CDXXXFA, R5F21367CNXXXFB, R5F21367CDXXXFB	48 Kbytes	04000h	–	4 Kbytes	013FFh
R5F21368CNFP, R5F21368CDFP, R5F21368CNFA, R5F21368CDFA, R5F21368CNFB, R5F21368CDFB, R5F21368CNXXXFP, R5F21368CDXXXFP, R5F21368CNXXXFA, R5F21368CDXXXFA, R5F21368CNXXXFB, R5F21368CDXXXFB	64 Kbytes	04000h	13FFFh	6 Kbytes	01BFFh
R5F2136ACNFP, R5F2136ACDFP, R5F2136ACNFA, R5F2136ACDFA, R5F2136ACNFB, R5F2136ACDFB, R5F2136ACNXXXFP, R5F2136ACDXXXFP, R5F2136ACNXXXFA, R5F2136ACDXXXFA, R5F2136ACNXXXFB, R5F2136ACDXXXFB	96 Kbytes	04000h	1BFFFh	8 Kbytes	023FFh
R5F2136CCNFP, R5F2136CCDFP, R5F2136CCNFA, R5F2136CCDFA, R5F2136CCNFB, R5F2136CCDFB, R5F2136CCNXXXFP, R5F2136CCDXXXFP, R5F2136CCNXXXFA, R5F2136CCDXXXFA, R5F2136CCNXXXFB, R5F2136CCDXXXFB	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map of R8C/36C Group

Table 4.6 SFR Information (6) (1)

Address	Register	Symbol	After Reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIORA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h	UART1 Transmit/Receive Mode Register	U1MR	00h
0161h	UART1 Bit Rate Register	U1BRG	XXh
0162h	UART1 Transmit Buffer Register	U1TB	XXh
0163h			XXh
0164h	UART1 Transmit/Receive Control Register 0	U1C0	00001000b
0165h	UART1 Transmit/Receive Control Register 1	U1C1	00000010b
0166h	UART1 Receive Buffer Register	U1RB	XXh
0167h			XXh
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h	Timer RG Mode Register	TRGMR	01000000b
0171h	Timer RG Count Control Register	TRGCNTC	00h
0172h	Timer RG Control Register	TRGCR	10000000b
0173h	Timer RG Interrupt Enable Register	TRGIER	11110000b
0174h	Timer RG Status Register	TRGSR	11100000b
0175h	Timer RG I/O Control Register	TRGIOR	00h
0176h	Timer RG Counter	TRG	00h
0177h			00h
0178h	Timer RG General Register A	TRGGRA	FFh
0179h			FFh
017Ah	Timer RG General Register B	TRGGRB	FFh
017Bh			FFh
017Ch	Timer RG General Register C	TRGGRC	FFh
017Dh			FFh
017Eh	Timer RG General Register D	TRGGRD	FFh
017Fh			FFh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.10 SFR Information (10) (1)

Address	Register	Symbol	After Reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2C8Eh			XXh
2C8Fh			XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
2C9Fh			XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACh			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

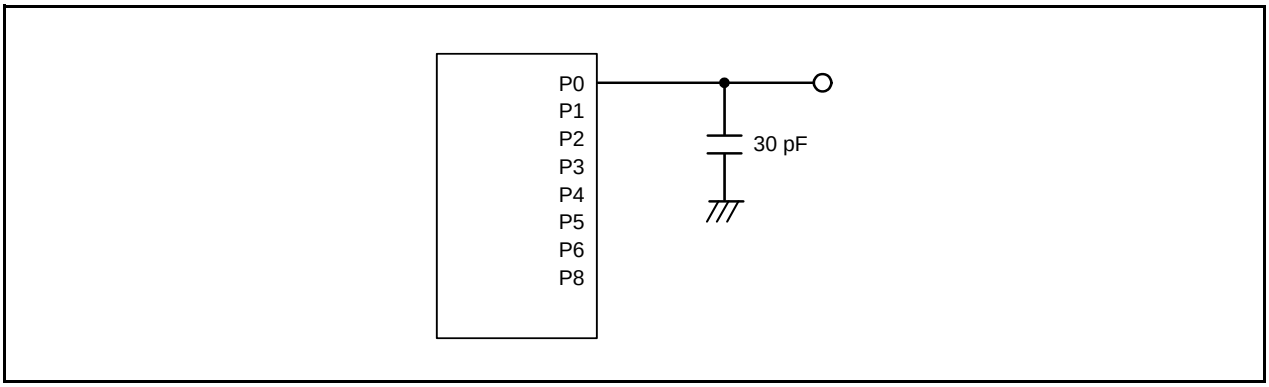


Figure 5.1 Ports P0 to P6, P8 Timing Measurement Circuit

Table 5.6 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
—	Program/erase endurance (2)		1,000 (3)	—	—	times
—	Byte program time		—	80	500	µs
—	Block erase time		—	0.3	—	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		—	—	5 + CPU clock × 3 cycles	ms
—	Interval from erase start/restart until following suspend request		0	—	—	µs
—	Time from suspend until erase restart		—	—	30 + CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly stopped until reading is enabled		—	—	30 + CPU clock × 1 cycle	µs
—	Program, erase voltage		2.7	—	5.5	V
—	Read voltage		1.8	—	5.5	V
—	Program, erase temperature		0	—	60	°C
—	Data hold time (7)	Ambient temperature = 55 °C	20	—	—	year

Notes:
1. V_{CC} = 2.7 to 5.5 V and T_{opr} = 0 to 60 °C, unless otherwise specified.
2. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed.)
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.8 Voltage Detection 0 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det0}	Voltage detection level Vdet0_0 (2)		1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 (2)		2.15	2.35	2.50	V
	Voltage detection level Vdet0_2 (2)		2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 (2)		3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time (4)	At the falling of V_{CC} from 5.0 V to (Vdet0_0 – 0.1) V	—	6	150	µs
—	Voltage detection circuit self power consumption	VCA25 = 1, V_{CC} = 5.0 V	—	1.5	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (3)		—	—	100	µs

Notes:
1. The measurement condition is V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85 °C (N version)/–40 to 85 °C (D version).
2. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
4. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.

Table 5.9 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det1}	Voltage detection level Vdet1_0 (2)	At the falling of V_{CC}	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 (2)	At the falling of V_{CC}	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 (2)	At the falling of V_{CC}	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 (2)	At the falling of V_{CC}	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 (2)	At the falling of V_{CC}	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 (2)	At the falling of V_{CC}	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 (2)	At the falling of V_{CC}	2.85	3.10	3.40	V
	Voltage detection level Vdet1_7 (2)	At the falling of V_{CC}	3.00	3.25	3.55	V
	Voltage detection level Vdet1_8 (2)	At the falling of V_{CC}	3.15	3.40	3.70	V
	Voltage detection level Vdet1_9 (2)	At the falling of V_{CC}	3.30	3.55	3.85	V
	Voltage detection level Vdet1_A (2)	At the falling of V_{CC}	3.45	3.70	4.00	V
	Voltage detection level Vdet1_B (2)	At the falling of V_{CC}	3.60	3.85	4.15	V
	Voltage detection level Vdet1_C (2)	At the falling of V_{CC}	3.75	4.00	4.30	V
	Voltage detection level Vdet1_D (2)	At the falling of V_{CC}	3.90	4.15	4.45	V
	Voltage detection level Vdet1_E (2)	At the falling of V_{CC}	4.05	4.30	4.60	V
	Voltage detection level Vdet1_F (2)	At the falling of V_{CC}	4.20	4.45	4.75	V
—	Hysteresis width at the rising of V_{CC} in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time (3)	At the falling of V_{CC} from 5.0 V to (Vdet1_0 – 0.1) V	—	60	150	µs
—	Voltage detection circuit self power consumption	VCA26 = 1, V_{CC} = 5.0 V	—	1.7	—	µA
$t_{d(E-A)}$	Waiting time until voltage detection circuit operation starts (4)		—	—	100	µs

Notes:
1. The measurement condition is V_{CC} = 1.8 to 5.5 V and T_{opr} = –20 to 85 °C (N version)/–40 to 85 °C (D version).
2. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
3. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
4. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.12 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency after reset	V_{CC} = 1.8 V to 5.5 V −20 °C ≤ T_{opr} ≤ 85 °C	38.4	40	41.6	MHz
		V_{CC} = 1.8 V to 5.5 V −40 °C ≤ T_{opr} ≤ 85 °C	38.0	40	42.0	MHz
	High-speed on-chip oscillator frequency when the FRA4 register correction value is written into the FRA1 register and the FRA5 register correction value into the FRA3 register (2)	V_{CC} = 1.8 V to 5.5 V −20 °C ≤ T_{opr} ≤ 85 °C	35.389	36.864	38.338	MHz
		V_{CC} = 1.8 V to 5.5 V −40 °C ≤ T_{opr} ≤ 85 °C	35.020	36.864	38.707	MHz
	High-speed on-chip oscillator frequency when the FRA6 register correction value is written into the FRA1 register and the FRA7 register correction value into the FRA3 register	V_{CC} = 1.8 V to 5.5 V −20 °C ≤ T_{opr} ≤ 85 °C	30.72	32	33.28	MHz
		V_{CC} = 1.8 V to 5.5 V −40 °C ≤ T_{opr} ≤ 85 °C	30.40	32	33.60	MHz
—	Oscillation stability time	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	0.5	3	ms
—	Self power consumption at oscillation	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	400	—	µA

Notes:
1. V_{CC} = 1.8 to 5.5 V and T_{opr} = −20 to 85 °C (N version)/−40 to 85 °C (D version), unless otherwise specified.
2. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.13 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		60	125	250	kHz
—	Oscillation stability time	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	30	100	µs
—	Self power consumption at oscillation	V_{CC} = 5.0 V, T_{opr} = 25 °C	—	2	—	µA

Note:
1. V_{CC} = 1.8 to 5.5 V and T_{opr} = −20 to 85 °C (N version)/−40 to 85 °C (D version), unless otherwise specified.

Table 5.14 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
$t_{d(P-R)}$	Time for internal power supply stabilization during power-on (2)		—	—	2,000	µs

Notes:
1. The measurement condition is V_{CC} = 1.8 to 5.5 V and T_{opr} = 25 °C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.

Table 5.15 Timing Requirements of Synchronous Serial Communication Unit (SSU)

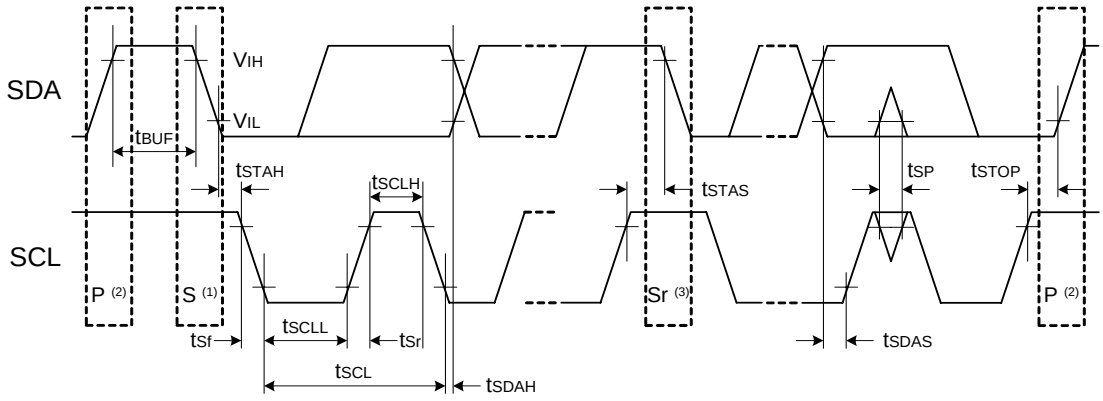
Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
t_{SUCYC}	SSCK clock cycle time			4	—	—	t_{CYC} (2)
t_{HI}	SSCK clock “H” width			0.4	—	0.6	t_{SUCYC}
t_{LO}	SSCK clock “L” width			0.4	—	0.6	t_{SUCYC}
t_{RISE}	SSCK clock rising time	Master		—	—	1	t_{CYC} (2)
		Slave		—	—	1	µs
t_{FALL}	SSCK clock falling time	Master		—	—	1	t_{CYC} (2)
		Slave		—	—	1	µs
t_{SU}	SSO, SSI data input setup time			100	—	—	ns
t_H	SSO, SSI data input hold time			1	—	—	t_{CYC} (2)
t_{LEAD}	$\overline{SCS}$ setup time	Slave		$1t_{CYC}$ + 50	—	—	ns
t_{LAG}	$\overline{SCS}$ hold time	Slave		$1t_{CYC}$ + 50	—	—	ns
t_{OD}	SSO, SSI data output delay time			—	—	1	t_{CYC} (2)
t_{SA}	SSI slave access time		2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	$1.5t_{CYC}$ + 100	ns
			1.8 V ≤ V_{CC} < 2.7 V	—	—	$1.5t_{CYC}$ + 200	ns
t_{OR}	SSI slave out open time		2.7 V ≤ V_{CC} ≤ 5.5 V	—	—	$1.5t_{CYC}$ + 100	ns
			1.8 V ≤ V_{CC} < 2.7 V	—	—	$1.5t_{CYC}$ + 200	ns

Notes:
1. V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{opr} = –20 to 85 °C (N version)/–40 to 85 °C (D version), unless otherwise specified.
2. $1t_{CYC}$ = 1/f1(s)

Table 5.16 Timing Requirements of I²C bus Interface

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{SCL}	SCL input cycle time		$12t_{CYC} + 600$ (2)	—	—	ns
t_{SCLH}	SCL input “H” width		$3t_{CYC} + 300$ (2)	—	—	ns
t_{SCLL}	SCL input “L” width		$5t_{CYC} + 500$ (2)	—	—	ns
t_{sf}	SCL, SDA input fall time		—	—	300	ns
t_{SP}	SCL, SDA input spike pulse rejection time		—	—	$1t_{CYC}$ (2)	ns
t_{BUF}	SDA input bus-free time		$5t_{CYC}$ (2)	—	—	ns
t_{STAH}	Start condition input hold time		$3t_{CYC}$ (2)	—	—	ns
t_{STAS}	Retransmit start condition input setup time		$3t_{CYC}$ (2)	—	—	ns
t_{STOP}	Stop condition input setup time		$3t_{CYC}$ (2)	—	—	ns
t_{SDAS}	Data input setup time		$1t_{CYC} + 40$ (2)	—	—	ns
t_{SDAH}	Data input hold time		10	—	—	ns

Notes:
1. V_{CC} = 1.8 to 5.5 V, V_{SS} = 0 V, and T_{opr} = –20 to 85 °C (N version)/–40 to 85 °C (D version), unless otherwise specified.
2. $1t_{CYC} = 1/f1(s)$



Notes:
1. Start condition
2. Stop condition
3. Retransmit start condition

Figure 5.7 I/O Timing of I²C bus Interface

Table 5.17 Electrical Characteristics (1) [4.2 V ≤ Vcc ≤ 5.5 V]

Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	Output "H" voltage	Other than XOUT	Drive capacity High V_{CC} = 5 V	I_{OH} = –20 mA	V_{CC} – 2.0	—	V_{CC}	V
			Drive capacity Low V_{CC} = 5 V	I_{OH} = –5 mA	V_{CC} – 2.0	—	V_{CC}	V
		XOUT	V_{CC} = 5 V	I_{OH} = –200 µA	1.0	—	V_{CC}	V
V_{OL}	Output "L" voltage	Other than XOUT	Drive capacity High V_{CC} = 5 V	I_{OL} = 20 mA	—	—	2.0	V
			Drive capacity Low V_{CC} = 5 V	I_{OL} = 5 mA	—	—	2.0	V
		XOUT	V_{CC} = 5 V	I_{OL} = 200 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{INT4}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRFI, TRGIOA, TRGIOB, $\overline{ADTRG}$, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.1	1.2	—	V
		$\overline{RESET}$			0.1	1.2	—	V
I_{IH}	Input "H" current		V_I = 5 V, V_{CC} = 5.0 V		—	—	5.0	µA
I_{IL}	Input "L" current		V_I = 0 V, V_{CC} = 5.0 V		—	—	–5.0	µA
R_{PULLUP}	Pull-up resistance		V_I = 0 V, V_{CC} = 5.0 V		25	50	100	kΩ
R_{fXIN}	Feedback resistance	XIN			—	0.3	—	MΩ
R_{fXCIN}	Feedback resistance	XCIN			—	8	—	MΩ
V_{RAM}	RAM hold voltage		During stop mode		1.8	—	—	V

Note:
1. 4.2 V ≤ V_{CC} ≤ 5.5 V, T_{opr} = –20 to 85 °C (N version)/–40 to 85 °C (D version), and f(XIN) = 20 MHz, unless otherwise specified.

Timing requirements (Unless Otherwise Specified: V_{CC} = 2.2 V, V_{SS} = 0 V, T_{opr} = 25 °C)

Table 5.33 External Clock Input (XOUT, XCIN)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	200	—	ns
$t_{WH(XOUT)}$	XOUT input “H” width	90	—	ns
$t_{WL(XOUT)}$	XOUT input “L” width	90	—	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	—	µs
$t_{WH(XCIN)}$	XCIN input “H” width	7	—	µs
$t_{WL(XCIN)}$	XCIN input “L” width	7	—	µs

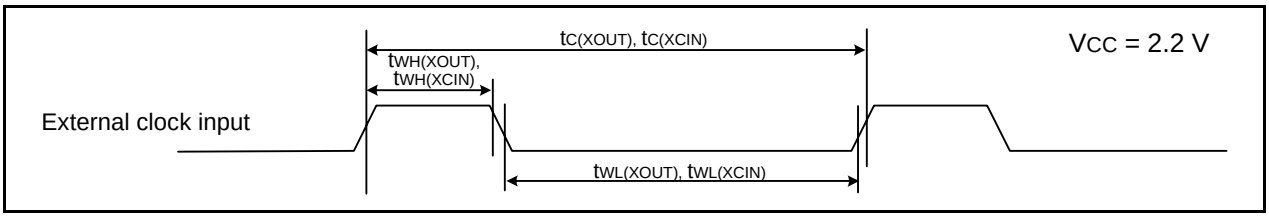


Figure 5.18 External Clock Input Timing Diagram when VCC = 2.2 V

Table 5.34 TRAIO Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	—	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	—	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	—	ns

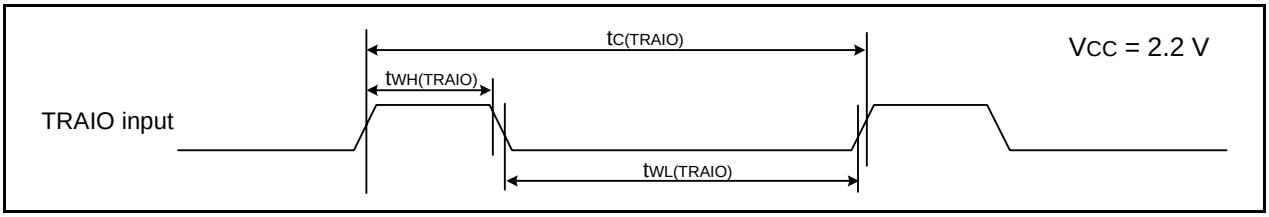


Figure 5.19 TRAIO Input Timing Diagram when Vcc = 2.2 V

Table 5.35 TRFI Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	2000 (1)	—	ns
$t_{WH(TRFI)}$	TRFI input “H” width	1000 (2)	—	ns
$t_{WL(TRFI)}$	TRFI input “L” width	1000 (2)	—	ns

Notes:
1. When using timer RF input capture mode, adjust the cycle time to (1/timer RF count source frequency × 3) or above.
2. When using timer RF input capture mode, adjust the pulse width to (1/timer RF count source frequency × 1.5) or above.

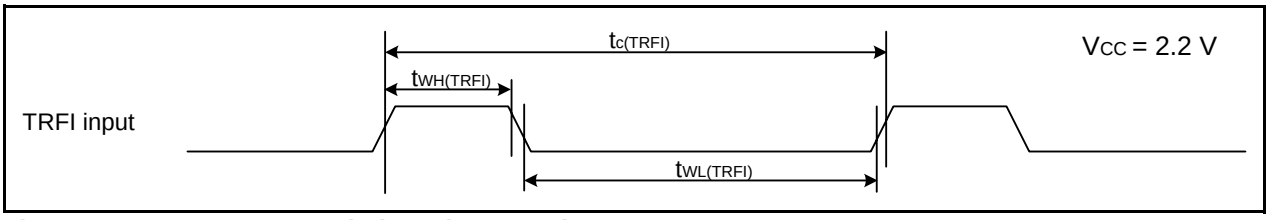


Figure 5.20 TRFI Input Timing Diagram when Vcc = 2.2 V

Table 5.36 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800	—	ns
$t_{W(CKH)}$	CLKi input “H” width	400	—	ns
$t_{W(CKL)}$	CLKi input “L” width	400	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	200	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	150	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

i = 0 to 2

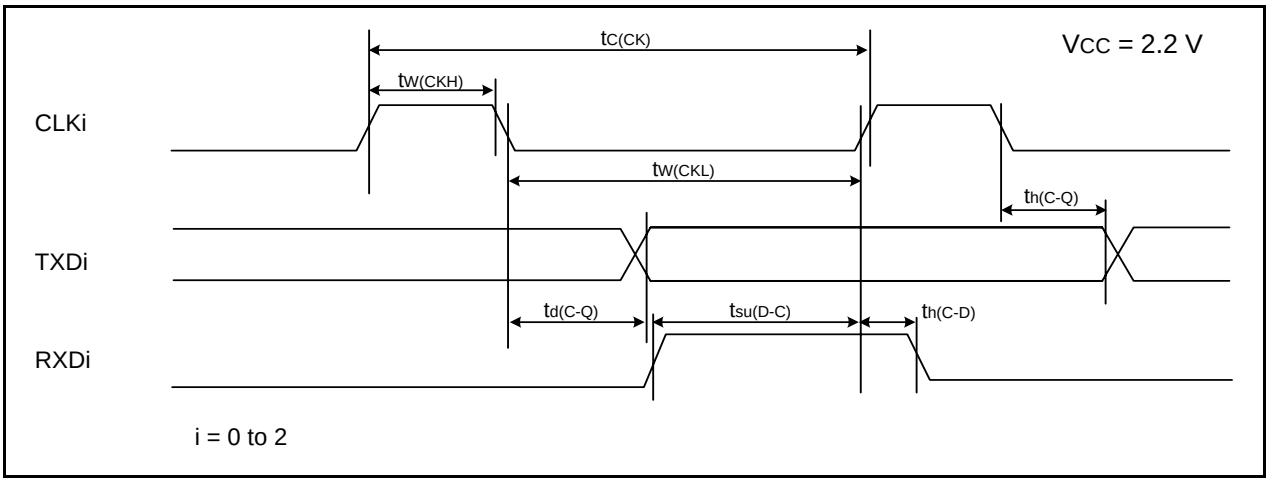


Figure 5.21 Serial Interface Timing Diagram when VCC = 2.2 V

Table 5.37 External Interrupt $\overline{INTi}$ (i = 0 to 4) Input, Key Input Interrupt $\overline{KIi}$ (i = 0 to 3)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{W(INH)}$	$\overline{INTi}$ input “H” width, $\overline{KIi}$ input “H” width	1000 (1)	—	ns
$t_{W(INL)}$	$\overline{INTi}$ input “L” width, $\overline{KIi}$ input “L” width	1000 (2)	—	ns

Notes:
1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

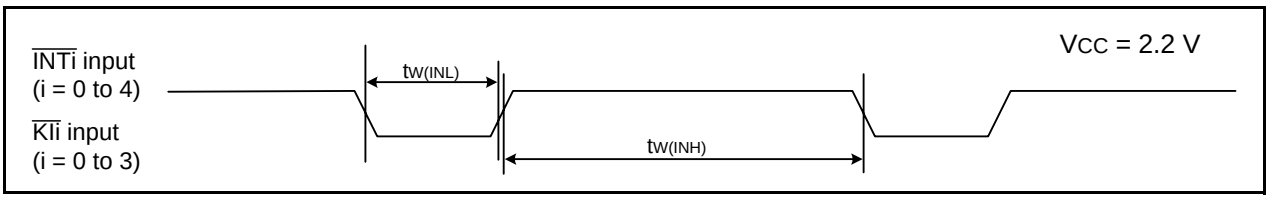
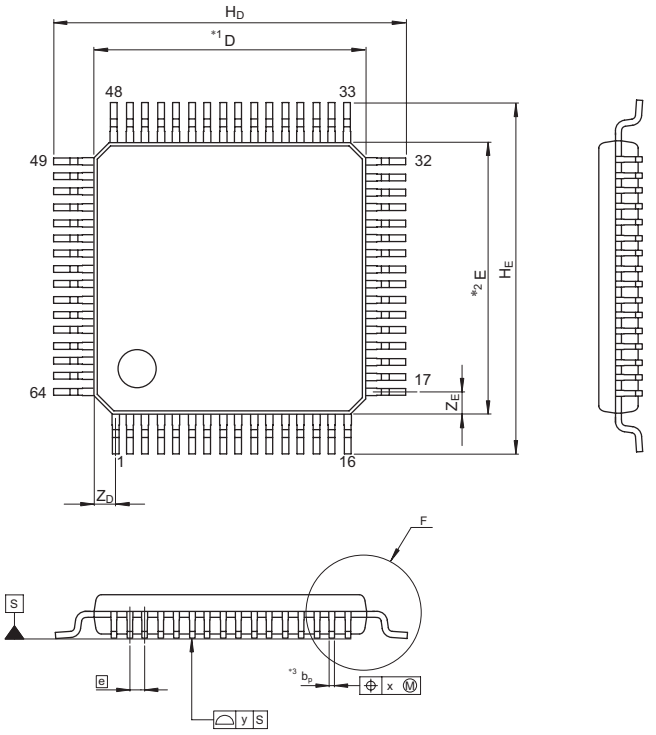
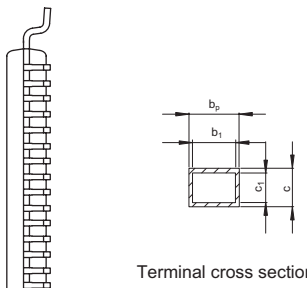


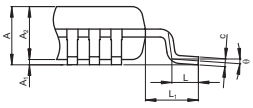
Figure 5.22 Input Timing Diagram for External Interrupt $\overline{INTi}$ and Key Input Interrupt $\overline{KIi}$ when VCC = 2.2 V

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-TQFP64-7x7-0.40	PTQP0064LB-A	—	0.14g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS"*1"AND"*2"
DO NOT INCLUDE MOLD FLASH
2. DIMENSION"*3"DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.00	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.20
A_1	0.05	0.10	0.15
b_p	0.13	0.18	0.23
b_1	—	0.16	—
c	0.12	0.17	0.22
c_1	—	0.15	—
θ	0°	—	8°
e	—	0.40	—
x	—	—	0.07
y	—	—	0.08
Z_D	—	0.50	—
Z_E	—	0.50	—
L	0.35	0.50	0.65
L_1	—	1.00	—

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

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